

Sub E!
C1 ✓ Claim 66, lines 1 and 2, after "camera system", please insert --component--.

120. (Amended) The imaging device according to claim 1, further comprising a gate stack over said substrate and beneath said insulating layer, wherein said gate stack is disposed over an insulating layer of silicon dioxide which is over said substrate.

121. (Amended) The imaging device according to claim 14, further comprising a gate stack over said substrate and beneath said insulating layer, wherein said gate stack is disposed over an insulating layer of silicon dioxide which is over said substrate.

122. (Amended) The imaging device according to claim 28, further comprising a gate stack over said substrate and beneath said insulating layer, wherein said gate stack is disposed over an insulating layer of silicon dioxide which is over said substrate.

123. (Amended) The imaging device according to claim 39, further comprising a gate stack over said substrate and beneath said insulating layer, wherein said gate stack is disposed over an insulating layer of silicon dioxide which is over said substrate.

124. (Amended) The imaging device according to claim 53, further comprising a gate stack over said substrate and beneath said insulating layer, wherein said gate stack is disposed over an insulating layer of silicon dioxide which is over said substrate.

Please add the following new claims:

C2 *Sub H2* *H* 125. (New) The imaging device according to claim 115, further comprising a gate stack over said substrate and beneath said insulating layer, wherein said gate stack is disposed over an insulating layer of silicon dioxide which is over said substrate.